

24 Volts Uniform 8mm Thin 3535 WRGB Led Strip For Neon Light Model: FSLRGBW-4T1-3535X120W8

Features 特征

- PLCC-6 Package.PLCC-6 封装
- Extremely wide viewing angle. 发光角度大
- Suitable for all SMT assembly and solder process.适用于所有的SMT组装和焊接工艺
- Available on tape and reel.适用于载带及卷轴
- Moisture sensitivity level: Level 3.防潮等级 Level 3
- Package:1000pcs/reel.包装每卷1000pcs
- RoHS compliant. 满足RoHS要求

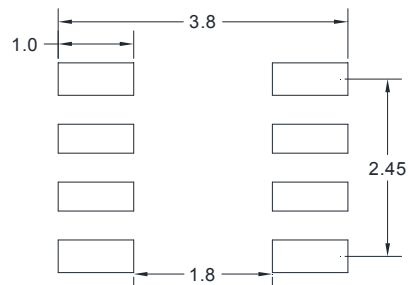
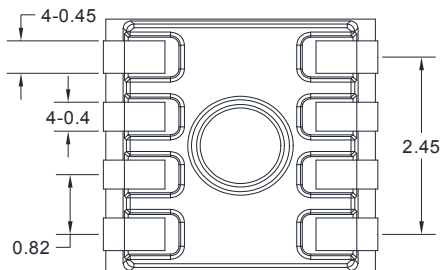
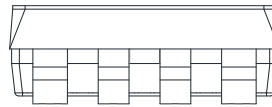
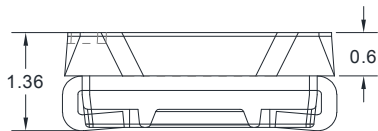
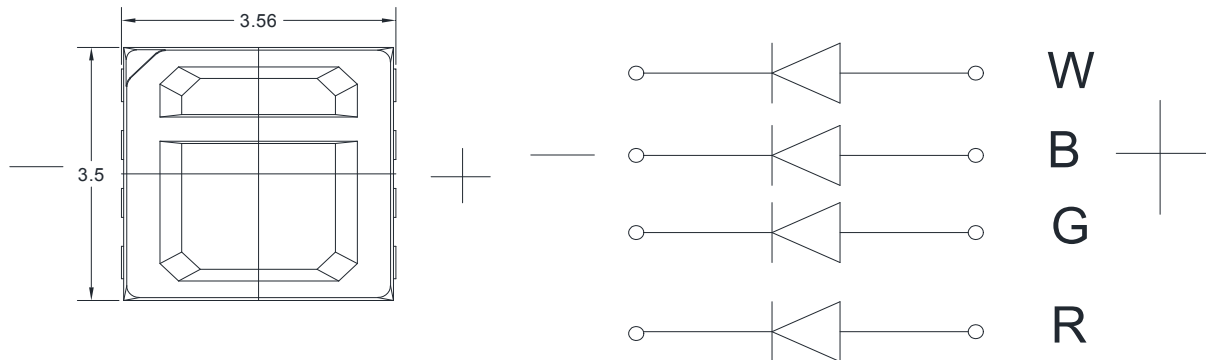
Description 描述

- The Red source color devices are made with AlGaInP on Substrate Light Emitting Diode
红光LED由AlGaInP四种元素芯片激发而成
- The Green source color devices are made with InGaN on Substrate Light Emitting Diode
绿光LED由InGaN三种元素芯片激发而成
- The Blue source color devices are made with InGaN on Substrate Light Emitting Diode
蓝光LED由InGaN三种元素芯片激发而成
- The White LED which was fabricated using a blue chip and phosphors.
白光LED由芯片激发荧光粉后，混光形成

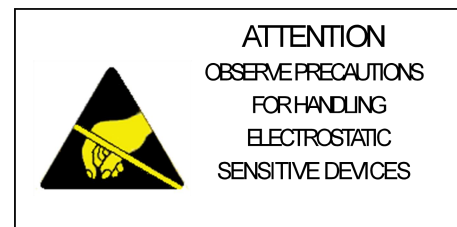
Applications 应用

- Optical indicator.光学指示
- Indoor display.室内显示
- Article color lamp, lamp belt. 彩色灯条、灯带
- Landscape lighting, Trademark logo.景观照明，招牌字
- General use. 其他应用

Package Dimension



Recommended Solder Pad



Note:

1. All dimensions units are millimeters
2. All dimensions tolerances are ± 0.2 mm unless otherwise noted.

Electrical / Optical Characteristics at Ta=25°C

Item 项目	Symbol 符号		test condition 测试条件	Value			unit 单位
				Min.	Max.	Typ.	
Forward Voltage	Vf	R	IF=20mA	1.9	2.1	---	V
				2.1	2.3	---	V
		G		2.7	2.9	---	V
				2.9	3.1	---	V
				3.1	3.3	---	V
				B	2.7	2.9	---
		2.9			3.1	---	V
		W		IF=20mA	2.7	3.1	---
-W2RGBQ3535E- B27/30/35/40/50/65W- GM	IV	R	IF=20mA	600	900	---	mcd
		G		1500	2000	---	mcd
		B		350	600	---	mcd
		2700K	IF=20mA	5	9	---	lm
		3000K	IF=20mA	5	9	---	lm
		3500K	IF=20mA	5	9	---	lm
		4000K	IF=20mA	5	9	---	lm
		5000K	IF=20mA	5	9	---	lm
		6500K	IF=20mA	5	9	---	lm
Dominant wavelength	WLD	R	IF=20mA	620	625	---	nm
		G		520	525	---	nm
		B		465	470	---	nm
		W		3800	4200	---	K
Reverse Current		VR=5V	IR	---	10	---	uA
Viewing Angle		2Θ1/2	IF=20mA	---	---	120	Deg
Color Rendering Index		CRI	IF=20mA	90	---	95	---

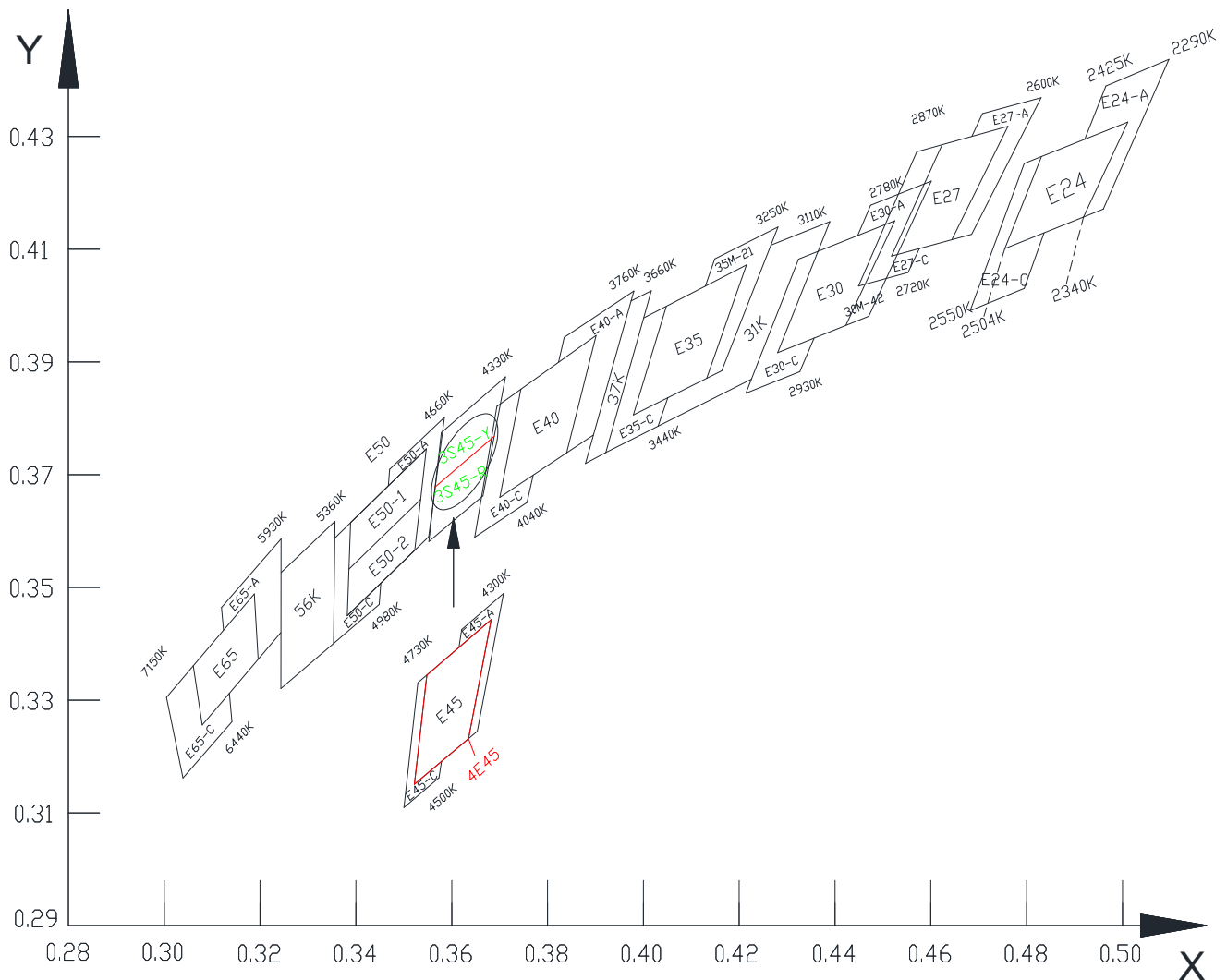
Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	Pd	250	mW
RGB Forward Current	IF	30	mA
Peak Forward Current	IFP	80	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge(HBM)	ESD	2000	V
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +100	°C
junction temperature	Tj	110	°C

Note:

1. 1/10 Duty cycle, 0.1ms pulse width.
2. The above forward voltage measurement allowance tolerance is $\pm 0.05V$.
3. The above wavelength measurement allowance tolerance is $\pm 1nm$.
4. the above luminous intensity measurement allowance tolerance $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of .
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate.

The Chromaticity Diagram



BIN CODE:

BIN CODE	X1	Y1	X2	Y2	X3	Y3	X4	Y4
E65	0.3061	0.3361	0.3188	0.3488	0.3196	0.3373	0.3079	0.3256
E50	0.3389	0.3615	0.3547	0.3746	0.3523	0.3566	0.3382	0.3450
E40	0.3745	0.3852	0.3902	0.3947	0.3840	0.3738	0.3700	0.3660
E35	0.4048	0.3999	0.4215	0.4072	0.4132	0.3871	0.3979	0.3806
E30	0.4365	0.4096	0.4525	0.4151	0.4423	0.3965	0.428	0.3917
E27	0.4624	0.4285	0.4761	0.4318	0.4644	0.4117	0.4518	0.4088

Characteristics Curves

Fig.1-Forward Voltage Vs. Forward Current

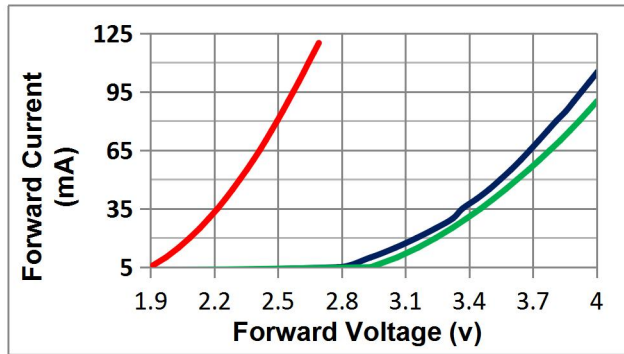


Fig.2-Forward Current Vs. Relative Intensity

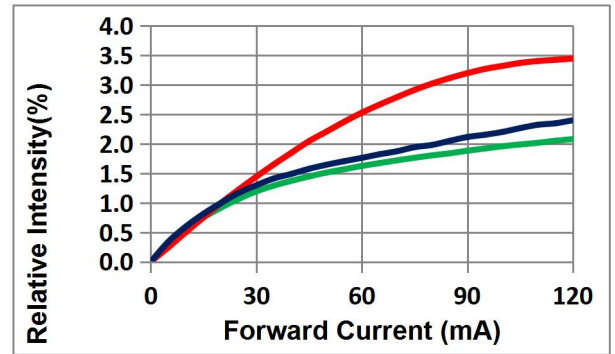


Fig.3-Temperature Vs. Relative Intensity

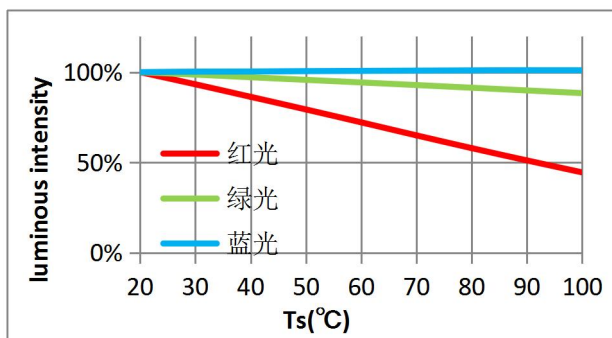


Fig.4- Spectrum Distribution

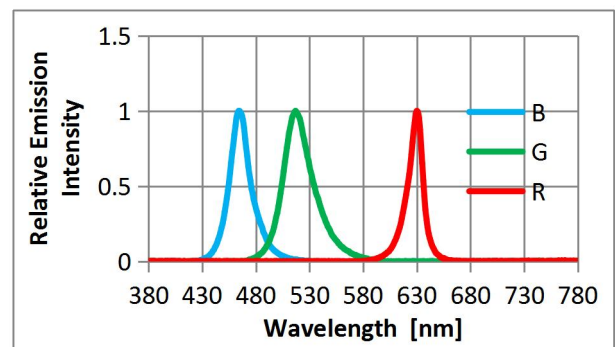


Fig.5-Forward Voltage Vs. Temperature

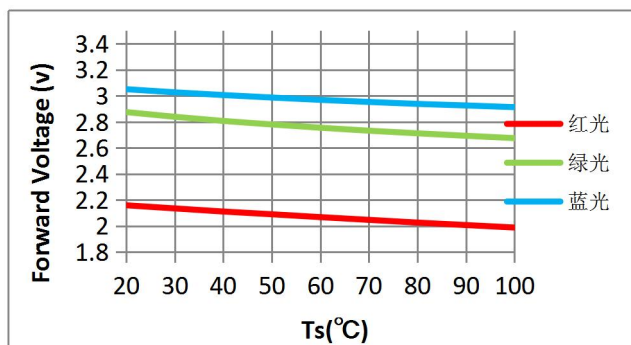
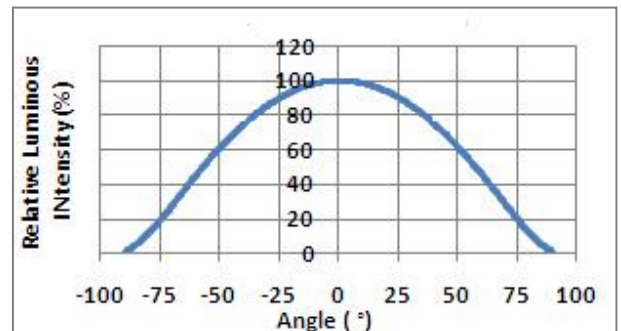


Fig.6-Radiation diagram



W1/W2 Typical Optical Characteristics Curves

Fig.1-Forward Voltage Vs. Forward Current

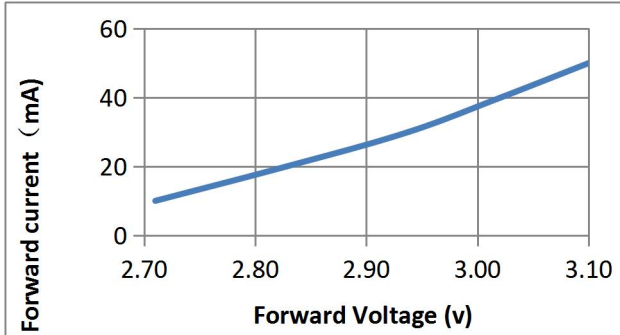


Fig.2-Forward Current Vs. Relative Intensity

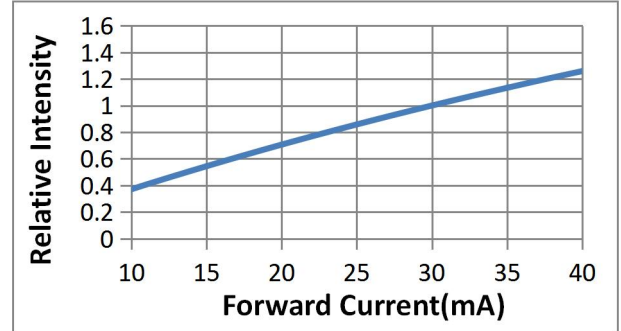


Fig.3- Temperature Vs. Relative Intensity

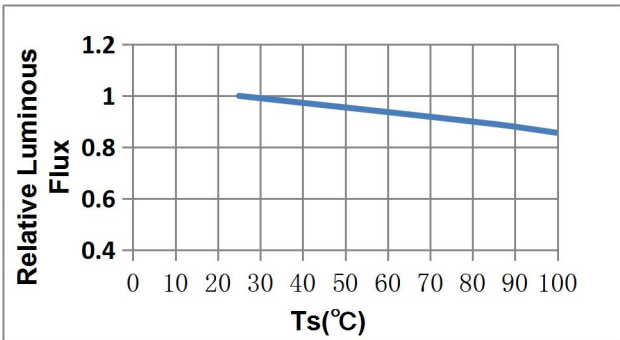


Fig.4- Temperature Vs. Forward Current

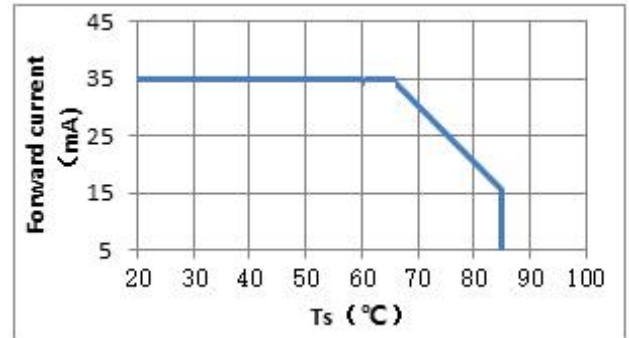


Fig.5-Forward Voltage Vs. Temperature

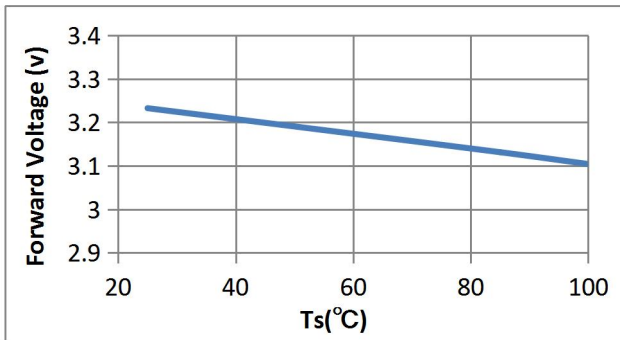


Fig.6-Radiation diagram

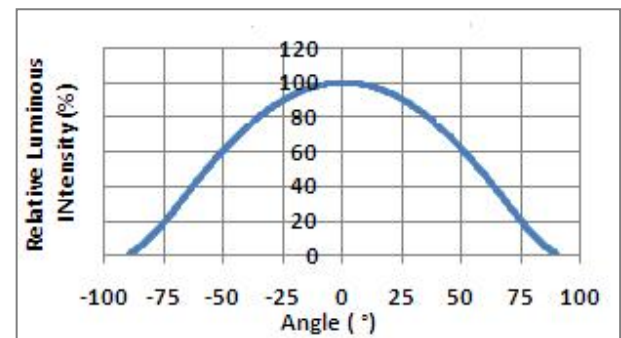
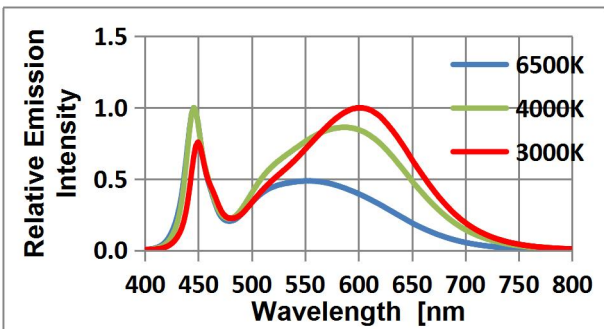


Fig.7- Spectrum Distribution



Note:

All the parameters and standards in the specification are based on standard test platform.

Reliability Test Items And Conditions

Test Items 项目	Ref.Standard 参考标准	Test Condition 测试条件	Time 时间	Quantity 数量	Ac/Re 接收/拒收
Reflow 回流焊	JESD22-B106	Temp:260℃ max T=10 sec	2times.	20Pcs.	0/1
Thermal Shock 冷热冲击	JESD22-A106	-40℃ 15min ↑↓ 100℃ 15min	200 cycle	20Pcs.	0/1
High Temperature Storage 高温保存	JESD22-A103	Temp:100℃	1000Hrs.	20Pcs.	0/1
Low Temperature Storage 低温保存	JESD22-A119	Temp:-40℃	1000Hrs.	20Pcs.	0/1
Life Test 常温通电	JESD22-A108	Ta=25℃ IF=80mA	1000Hrs.	20Pcs.	0/1
High Temperature High Humidity Life Test 高温高湿通电	JESD22-A101	60℃ / 90%RH IF=80mA	1000Hrs.	10Pcs.	0/1

Criteria For Judging Damage

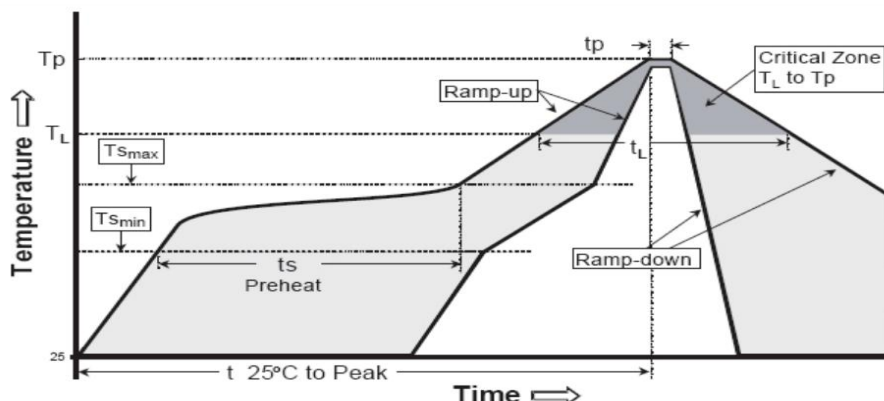
Test Items 项目	Symbol 符号	Test Condition 测试条件	Criteria For Judgement 判定标准	Applicable project 适用项目
Forward Voltage 正向电压	Vf	IF=80mA	$\leq \pm 10\%$	Reflow High and Low Temperature Storage Life Test
Luminous Intensity 光强	IV	IF=80mA	Maintenance $\geq 70\%$ 光强维持率	
Lamp bead light test 灯珠点亮测试	/	IF=80mA	No open circuit, shortcircuit or flicke 无开路,短路, 闪变	High Temperature High Humidity Life Test TestHigh Temperature Life Test

U.S.L: Upper standard level 规格上限 L.S.L: Lower standard level 规格下限

1>.The Reliability tests are based on existing test platform. 信赖性测试基于 现有的测试平台。

2>.The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license. 以上技术数据仅为产品的典型值，只作为参考，不作为任何应用条件及应用方式的保证。

SMT Reflow Soldering Instructions



平均升温速度 (Tsmax 至 Tp)	最高 3 °C/ 秒	最高 3 °C/ 秒
预热：最低温度 (Tsmin)	100 °C	150 °C
预热：最高温度 (Tsmax)	150 °C	200 °C
预热：时间 (tsmin 至 tsmax)	60 - 120 秒	60 - 180 秒
限时维持高温：温度 (TL)	183 °C	217 °C
限时维持高温：时间 (tL)	60 - 150 秒	60 - 150 秒
峰值 / 分类温度 (Tp)	215 °C	260 °C
与实际峰值温度 (tp) 相差 5 °C 以内的保持时间	10 - 30 秒	20 - 40 秒
降温速度	最高 6 °C/ 秒	最高 6 °C/ 秒
25 °C 升至峰值温度所需时间	最多 6 分钟	最多 8 分钟

1.Reflow soldering should not be done more than two times. In the case of more than 24 hours passed soldering after first, LEDs will be damaged. 回流焊次数不可以超两次，两次回流焊时间间隔如超过24小时，LED可能由于吸湿而损坏

2.When soldering , do not put stress on the LEDs during heating当焊接时，不要在材料受热时用力压胶体表面。

■ Soldering Iron 烙铁焊接

1.When hand soldering, keep the temperature of iron below less 300°C less than 3 seconds

当手工焊接时，烙铁的温度必须小于300°C，时间不可超过3秒。

2.The hand solder should be done only one time.手工焊接只可焊接一次。

■ Repairing 修补

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing. LED回流焊后不应该修复，当必须修复时，必须使用双头烙铁，而且事先应确认此种方式会不会损坏LED本身的特性。

■ Cautions 注意事项

1.The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED封装胶为硅胶，表面较软，用力按压胶体表面会影响LED可靠性，因此应有预防措施避免在按压器件，当使用吸嘴时，胶体表面的压力应是恰当的。

2. Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED灯珠不要焊接在弯曲的PCB板上，焊接之后，也不要弯折线路板。

3. Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

回流焊之后冷却过程中，不要对材料施加外力，也不要震动，回流焊后，不要采用激剧冷却的方式。

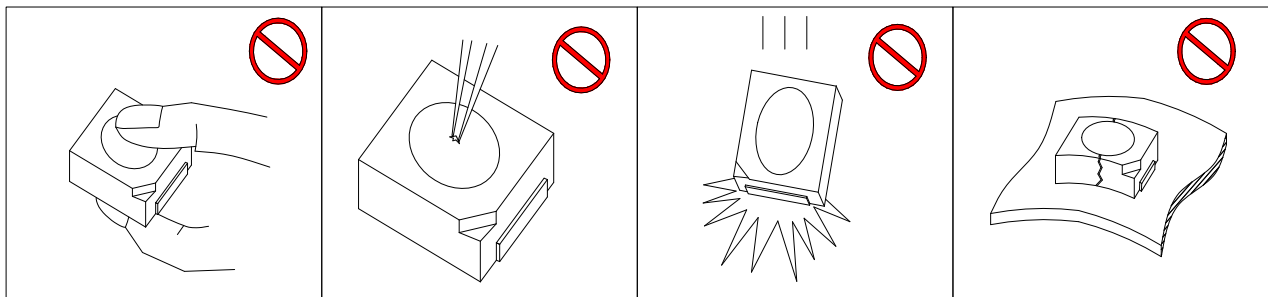
Handling Precautions

1>.LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.LED工作环境及与LED适配的材料中，硫元素及化合物成份不可超过100PPM，单一的溴元素含量要求小于900PPM，单一氯元素含量要求小于900PPM，溴元素与氯元素总含量必须小于1500PPM（检测含量为与LED直接接触面上元素含量）。

2>.VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor. 应用套件中的挥发性物质会渗透到LED内部，可能对LED性能或者可靠性不利，在通电情况下会加剧影响。因此客户需提前验证，避免套件材料或其他组装原物料存在未经验证的挥发性物质，针对特定的用途和使用环境， 建议对所有的物质和材料进行相容性的测试。

3>.Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

通过使用适当的工具从材料侧面夹取，不可直接用手或尖锐金属压胶体表面，它可能会损坏内部电路。



4>. In designing a circuit,the current through each LED must be exceed the absolute maximum rating specified for each LED.In the meanwhile,resistors for protection should be applied,otherwise slight voltage shift will cause big current change,burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF.If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

设计电路时，通过LED的电流不能超过规定的最大值，同时，还需使用保护电阻，否则，微小的电压变化将会引起较大电流变化，可能导致产品损毁。电路设计必须保证只有在开启或者关闭的时候出现正向电压的变化，不要施加反压，否则会损坏LED。

5>.Thermal Design is paramount importance because heat generation may result in the Characteristics decline,such as brightness decreased,Color change and so on.Please consider the heat generation of the LEDs when making the system design.LED容易因为自身的发热和环境的温度改变而改变，温度升高会降低LED发光效率，影响发光颜色，所以在设计时应充分考虑散热问题。

6> .Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust , requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED. 与其他封装胶相比，硅胶通常较软，表面易吸附脏物，应用时应特别注意，当对产品洁净度要求较高时，应当采用恰当的清洗方式，我们推荐用异丙醇作清洗剂，如需要用到其他清洗剂，必须保证不会破坏封装体，超声清洗可能会对LED带来损害，不推荐这种清洗方式。

7> .To avoid the moisture penetration, we recommend store in a dry box with a desiccant. The recommended storage temperature range is 5°C to 30°C and a maximum humidity of RH50%. If the color of the desiccant changes, components should be dried for 10-12hr at 60±5°C.为了避免湿气进入，产品应该保存在干燥的地方，同时需要使用干燥剂，推荐的储存温度是5°C到30°C，最大湿度不能超过50%，如果湿度卡指示变色，使用前需要烘烤10-12小时，烘烤温度为60±5°C。

8> .Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). LED为半导体器件，对静电敏感，生产和使用时需要做好防护。

9>.There should be Revalidated when there is any change on the use condition(like fixture type, raw material, Radiating change) after the approval.产品承认后，如需变更使用环境条件（如：转换产品种类和结构），必须重新验证。

10>.When you have special quality requirement for the product, please kindly contact to our sales.

对产品有特殊质量要求时，请提前咨询销售人员以取得相关信息。

11>.客户在应用LED时，需参考此规格书参数及使用环境要求，未经验证情况下超出参数或标准条件使用，不作任何品质担保。

12>.The customer shall not disassemble or analyze the LEDs without having consent from . When defective LEDs are found, the customer shall inform in writing directly before disassembling or analysis.

在取得 的同意前，客户不应对产品进行拆解分析，如发现失效产品，请直接书面通知。

13>.Other points for attention, please refer to our LED user manual.

其它注意事项请参照 LED 使用手册。